



Vincotech

10-FY07NIA100S503-M515F58 datasheet

flowNPC 1

650 V / 100 A

Features

- NPC inverter topology
- Optimized for 1200 Vdc applications
- High-speed IGBT
- Low inductive design with integrated DC capacitor
- flow 1 12mm package
- NTC

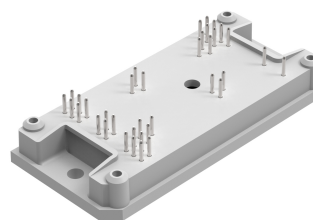
Target applications

- Solar Inverters
- UPS

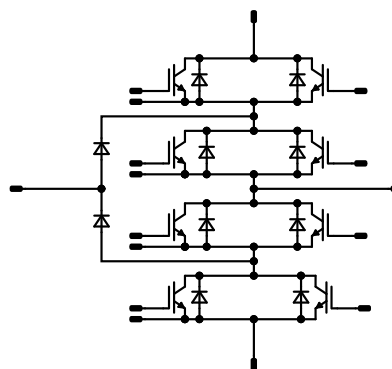
Types

- 10-FY07NIA100S503-M515F58

flow 1 12 mm housing



Schematic





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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
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Buck Switch

Collector-emitter voltage	V_{CES}		650	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	90	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	300	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	133	W
Gate-emitter voltage	V_{GES}		± 20	V
Maximum junction temperature	T_{jmax}		175	°C

Buck Diode

Peak repetitive reverse voltage	V_{RRM}		650	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	76	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	106	W
Maximum junction temperature	T_{jmax}		175	°C

Boost Switch

Collector-emitter voltage	V_{CES}		650	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	129	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	450	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	133	W
Gate-emitter voltage	V_{GES}		± 20	V
Maximum junction temperature	T_{jmax}		175	°C



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Maximum Ratings

$T_j = 25\text{ °C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Boost Diode				
Peak repetitive reverse voltage	V_{RRM}		650	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	85	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	122	W
Maximum junction temperature	T_{jmax}		175	°C

Boost Sw. Inv. Diode

Peak repetitive reverse voltage	V_{RRM}		650	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	85	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	200	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80\text{ °C}$	122	W
Maximum junction temperature	T_{jmax}		175	°C

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	°C
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	°C

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage* $t_p = 2\text{ s}$	6000	V
Isolation voltage	V_{isol}	AC Voltage $t_p = 1\text{ min}$	2500	V
Creepage distance			min. 12,7	mm
Clearance			7,92	mm
Comparative Tracking Index	CTI		≥ 200	

*100 % tested in production



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Buck Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,001	25	3,2	4	4,8	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		100	25 125 150		1,39 1,48 1,51	1,75 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	650		25			100	µA
Gate-emitter leakage current	I_{GES}		20	0		25			200	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	$f = 1 \text{ Mhz}$	0	25		25		6200		pF
Output capacitance	C_{oes}							176		pF
Reverse transfer capacitance	C_{res}							24		pF
Gate charge	Q_g	$V_{CC} = 520 \text{ V}$	15		100	25		240		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4 \text{ W/mK}$ (PSX)						0,72		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 4 \Omega$ $R_{goff} = 4 \Omega$	± 15	350	100	25 125 150		72 74 73		ns
Rise time	t_r					25 125 150		11 11 12		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		98 115 118		ns
Fall time	t_f					25 125 150		14,78 26,49 28,9		ns
Turn-on energy (per pulse)	E_{on}					25 125 150		0,661 0,951 1,03		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		0,903 1,4 1,53		mWs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]		Min	Typ	Max	

Buck Diode

Static

Forward voltage	V_F			100	25 125 150			1,6 1,58 1,57	1,92 ⁽¹⁾	V
Reverse leakage current	I_R	$V_i = 650$ V			25				5,3	µA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						0,9		K/W
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Dynamic

Peak recovery current	I_{RRM}	$di/dt=10159$ A/µs $di/dt=8829$ A/µs $di/dt=8697$ A/µs	± 15	350	100	25 125 150		113,29 146,96 154,89		A
Reverse recovery time	t_{rr}					25 125 150		48,1 82,23 92,26		ns
Recovered charge	Q_r					25 125 150		3,14 6,11 6,87		µC
Reverse recovered energy	E_{rec}					25 125 150		0,837 1,63 1,81		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		4040 3052 3359		A/µs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Boost Switch

Static

Gate-emitter threshold voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}$			0,002	25	4,2	5	5,8	V
Collector-emitter saturation voltage	$V_{CE(sat)}$		15		150	25 125 150		1,1 1,09 1,09	1,45 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	650		25			80	μA
Gate-emitter leakage current	I_{GES}		20	0		25			200	nA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{ies}	$f = 1 \text{ Mhz}$	0	25		25		23250		pF
Reverse transfer capacitance	C_{res}							60		pF
Gate charge	Q_g		15	520	150	25		872		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4 \text{ W/mK}$ (PSX)						0,72		K/W
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Dynamic

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 4 \Omega$ $R_{goff} = 4 \Omega$	± 15	350	90	25 125 150		205,8 205,2 205		ns
Rise time	t_r					25 125 150		10,4 12,4 12,8		ns
Turn-off delay time	$t_{d(off)}$					25 125 150		302,2 346 372		ns
Fall time	t_f					25 125 150		56,75 93,58 111,01		ns
Turn-on energy (per pulse)	E_{on}					25 125 150		0,58 0,586 0,605		mWs
Turn-off energy (per pulse)	E_{off}					25 125 150		4,57 6,97 7,51		mWs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Boost Diode

Static

Forward voltage	V_F				100	25 150	1,18	1,78 1,57	1,82 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 650$ V				25			1,2	µA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						0,78		K/W
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Dynamic

Peak recovery current	I_{RRM}	$di/dt=10304$ A/µs $di/dt=8191$ A/µs $di/dt=8639$ A/µs	±15	350	90	25 125 150		104,99 132,31 139,28		A
Reverse recovery time	t_{rr}					25 125 150		133,73 193,51 202,62		ns
Recovered charge	Q_r					25 125 150		4,32 8,37 9,5		µC
Reverse recovered energy	E_{rec}					25 125 150		1,08 2,36 2,7		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		7314 3676 3353		A/µs



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Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	

Boost Sw. Inv. Diode

Static

Forward voltage	V_F				100	25 150	1,18	1,78 1,57	1,82 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 650$ V				25			1,2	μA

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						0,78		K/W
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Thermistor

Static

Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	$R_{100} = 1484$ Ω				100	-5		5	%
Power dissipation	P							5		mW
Power dissipation constant	d					25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ± 1 %						3962		K
B-value	$B_{(25/100)}$	Tol. ± 1 %						4000		K
Vincotech Thermistor Reference									I	

⁽¹⁾ Value at chip level

⁽²⁾ Only valid with pre-applied Vincotech thermal interface material.



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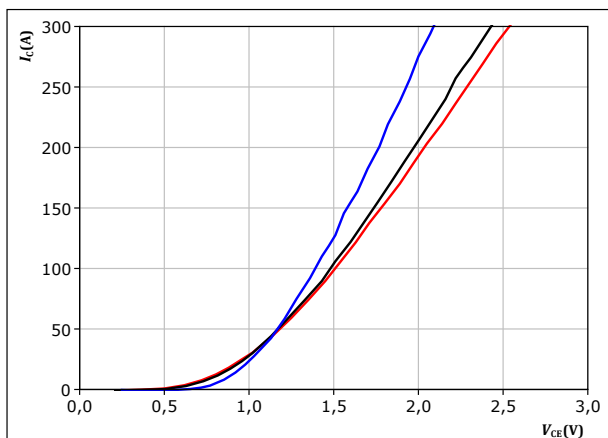
Buck Switch Characteristics

figure 1.

IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



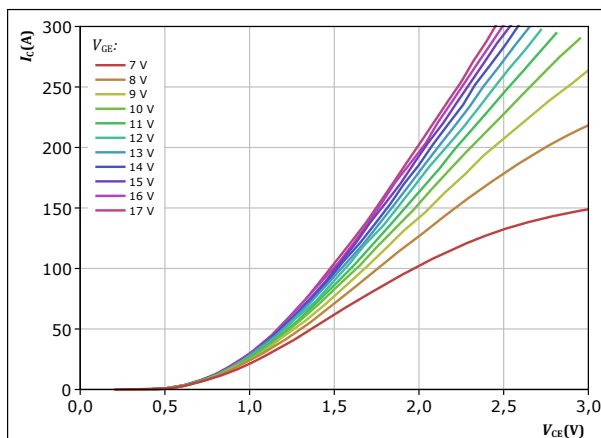
$t_p = 250 \mu s$
 $V_{GE} = 15 V$
 $T_j: 25^\circ C, 125^\circ C, 150^\circ C$

figure 2.

IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$



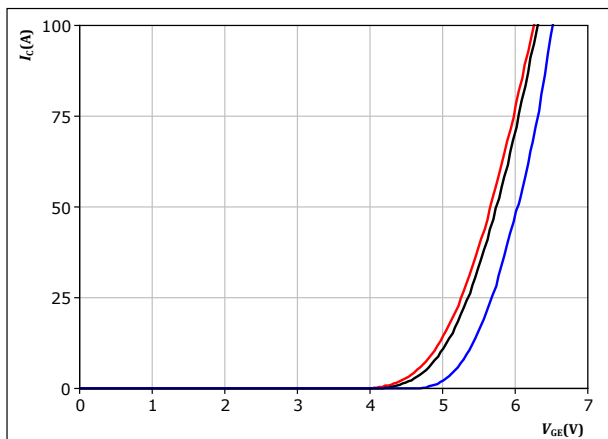
$t_p = 250 \mu s$
 $T_j = 150^\circ C$
 V_{GE} from 7 V to 17 V in steps of 1 V

figure 3.

IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$



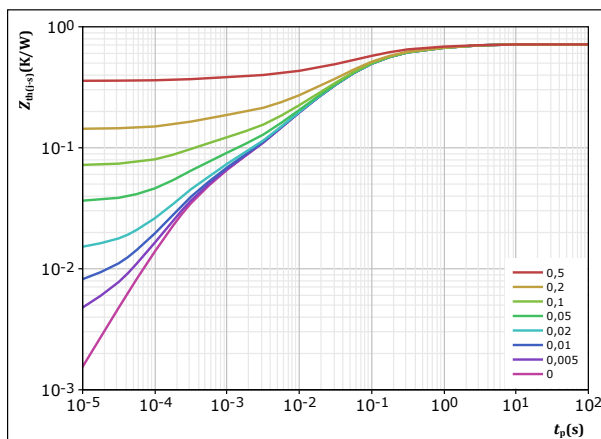
$t_p = 250 \mu s$
 $V_{CE} = 10 V$
 $T_j: 25^\circ C, 125^\circ C, 150^\circ C$

figure 4.

IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,715 K/W$
IGBT thermal model values

$R (K/W)$	$\tau (s)$
7,52E-02	1,73E+00
1,31E-01	2,44E-01
3,01E-01	6,32E-02
1,21E-01	1,39E-02
4,30E-02	3,50E-03
4,35E-02	3,33E-04



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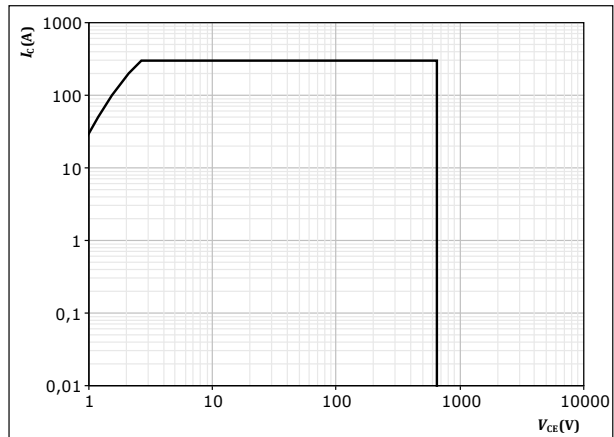
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Buck Switch Characteristics

figure 5. IGBT

Safe operating area

$$I_C = f(V_{CE})$$



$D = \text{single pulse}$

$T_s = 80 \text{ } ^\circ\text{C}$
 $V_{GE} = 15 \text{ V}$
 $T_j = T_{jmax}$



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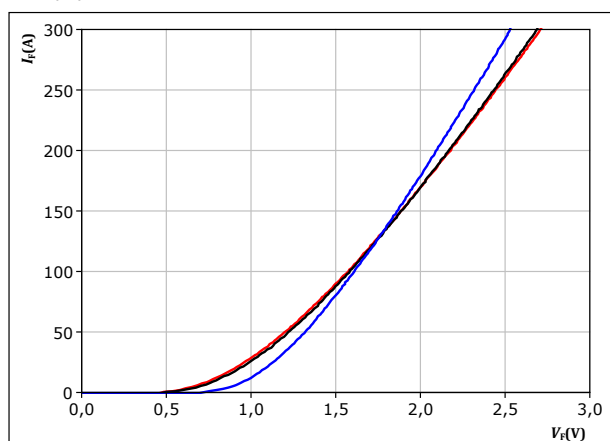
Buck Diode Characteristics

figure 6.

FWD

Typical forward characteristics

$$I_F = f(V_F)$$



$t_p = 250 \mu s$

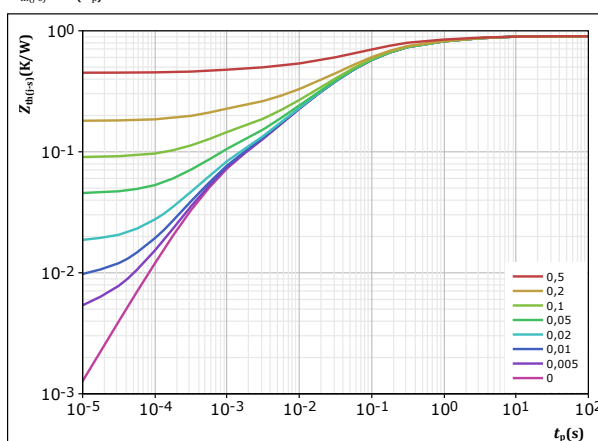
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 7.

FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$D = t_p / T$
 $R_{th(j-s)} = 0,9$ K/W
FWD thermal model values

R (K/W)	τ (s)
$7,42E-02$	$3,64E+00$
$1,41E-01$	$5,85E-01$
$3,41E-01$	$1,04E-01$
$1,94E-01$	$2,64E-02$
$9,09E-02$	$6,04E-03$
$5,85E-02$	$5,72E-04$



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Boost Switch Characteristics

figure 8. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

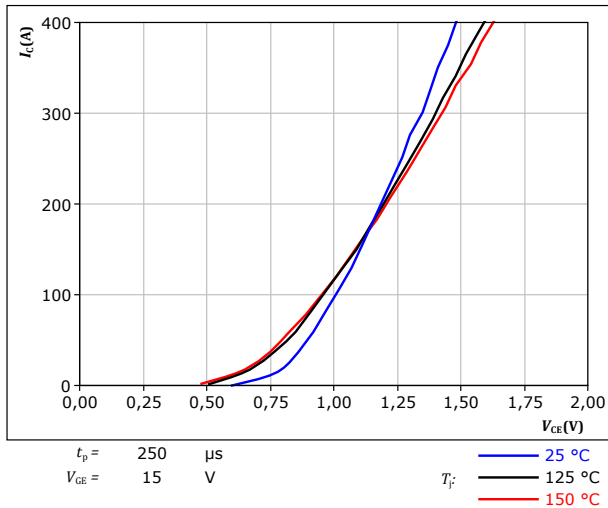


figure 9. IGBT

Typical output characteristics

$$I_C = f(V_{CE})$$

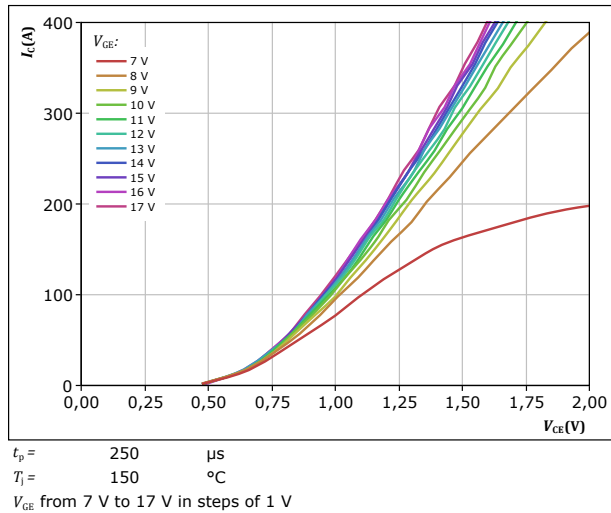


figure 10. IGBT

Typical transfer characteristics

$$I_C = f(V_{GE})$$

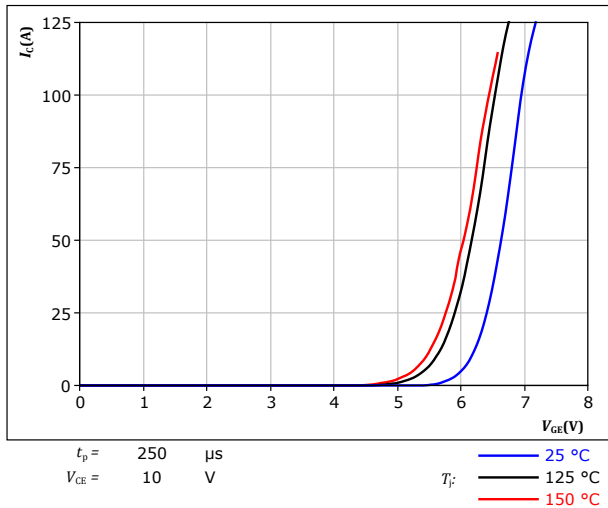
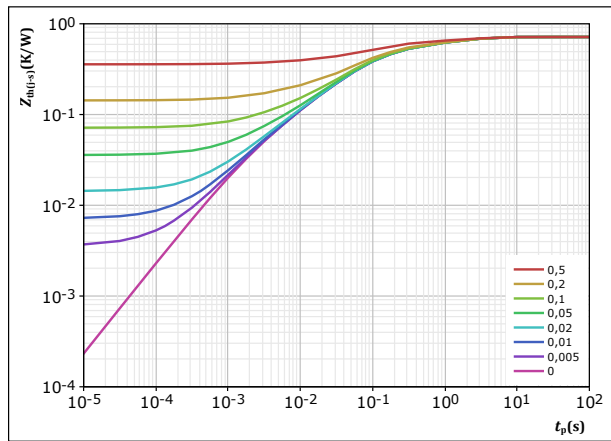


figure 11. IGBT

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



IGBT thermal model values	
R (K/W)	τ (s)
1,29E-01	2,09E+00
1,33E-01	4,46E-01
3,21E-01	8,45E-02
6,42E-02	2,97E-02
5,12E-02	7,88E-03
1,68E-02	1,62E-03



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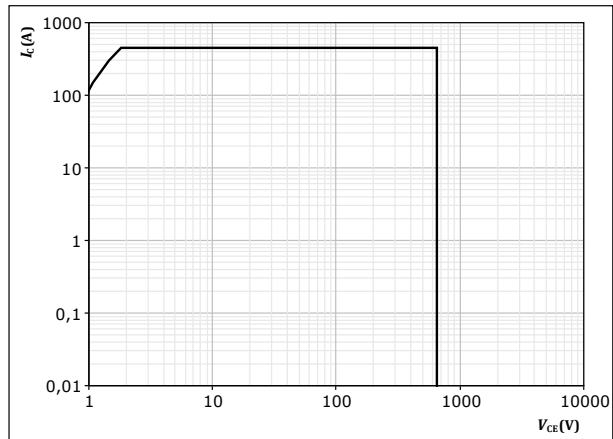
Boost Switch Characteristics

figure 12.

IGBT

Safe operating area

$I_C = f(V_{CE})$



$D = \text{single pulse}$

$T_s = 80 \text{ } ^\circ\text{C}$
 $V_{GE} = 15 \text{ V}$
 $T_j = T_{jmax}$



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Boost Diode Characteristics

figure 13.

FWD

Typical forward characteristics

$$I_F = f(V_F)$$

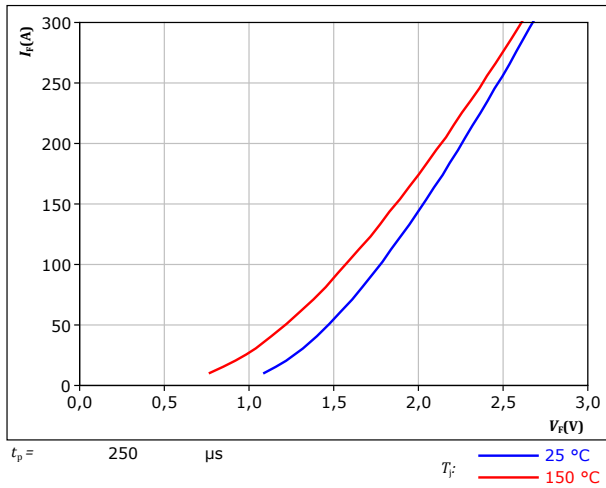
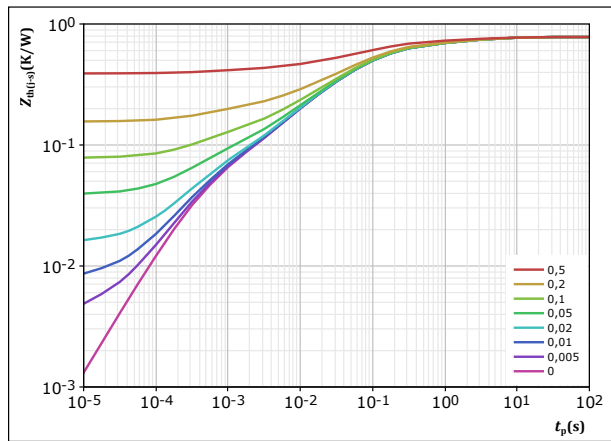


figure 14.

FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



$$D = \frac{t_p}{T}$$
$$R_{th(j-s)} = 0,78 \text{ K/W}$$

FWD thermal model values

R (K/W)	τ (s)
5,76E-02	5,42E+00
8,79E-02	1,09E+00
2,14E-01	1,59E-01
2,31E-01	4,95E-02
1,16E-01	1,05E-02
3,20E-02	2,39E-03
4,19E-02	4,10E-04



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Boost Sw. Inv. Diode Characteristics

figure 15. FWD

Typical forward characteristics

$$I_F = f(V_F)$$

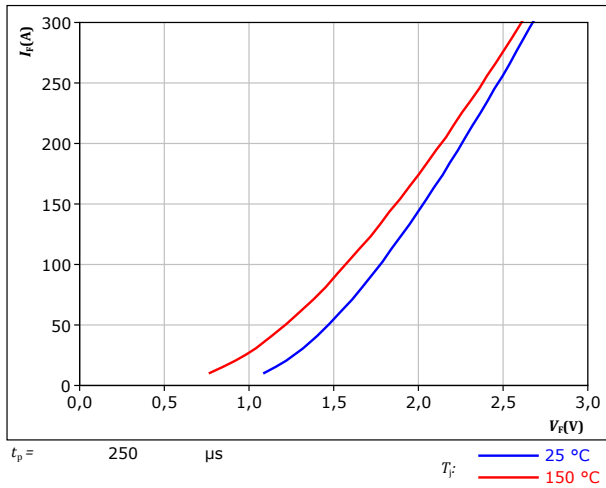
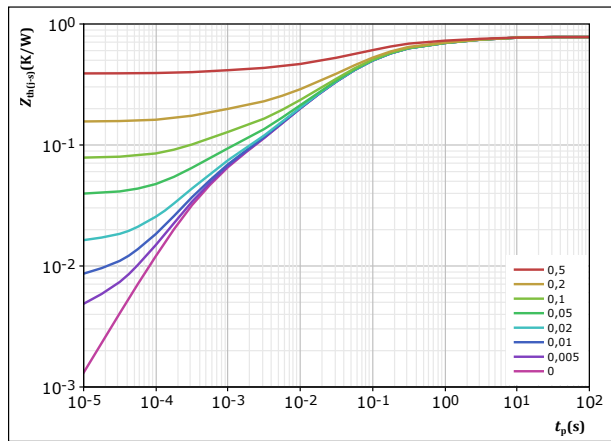


figure 16. FWD

Transient thermal impedance as a function of pulse width

$$Z_{th(j-s)} = f(t_p)$$



FWD thermal model values

$R \text{ (K/W)}$	$\tau \text{ (s)}$
5,76E-02	5,42E+00
8,79E-02	1,09E+00
2,14E-01	1,59E-01
2,31E-01	4,95E-02
1,16E-01	1,05E-02
3,20E-02	2,39E-03
4,19E-02	4,10E-04



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Thermistor Characteristics

figure 17.

Thermistor

Typical NTC characteristic as function of temperature

$$R_T = f(T)$$





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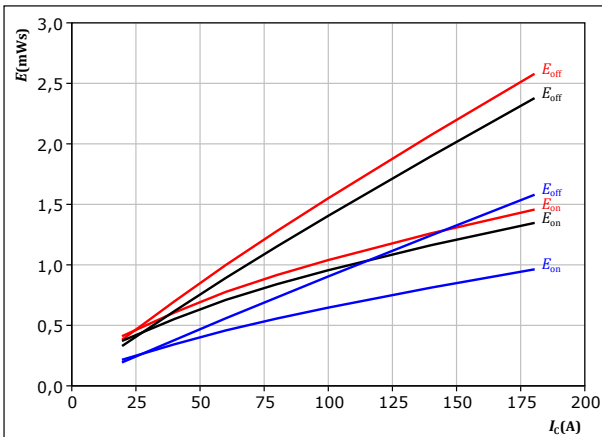
Buck Switching Characteristics

figure 18.

IGBT

Typical switching energy losses as a function of collector current

$$E = f(I_C)$$



With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$
 $R_{goff} = 4 \text{ } \Omega$

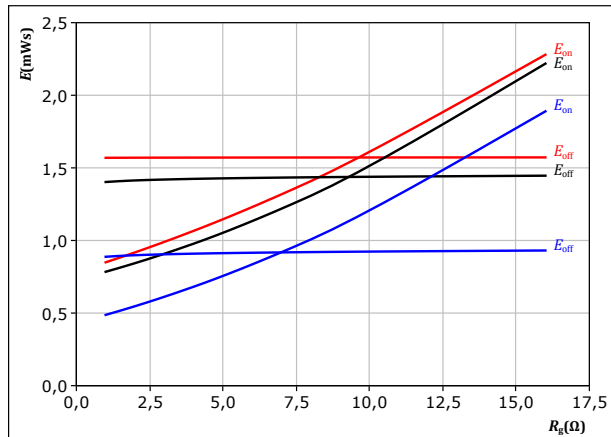
T_j : — 25 °C
— 125 °C
— 150 °C

figure 19.

IGBT

Typical switching energy losses as a function of gate resistor

$$E = f(R_g)$$



With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 100 \text{ A}$

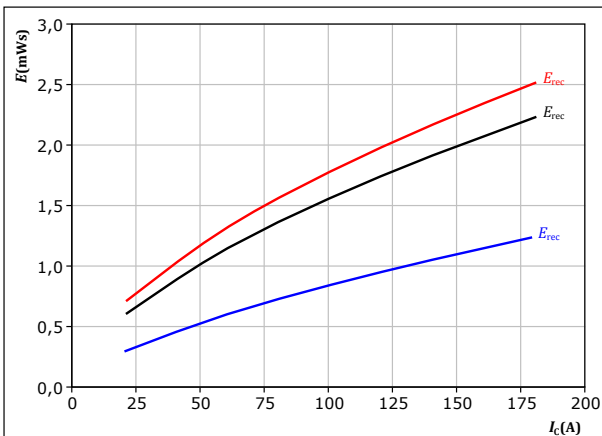
T_j : — 25 °C
— 125 °C
— 150 °C

figure 20.

FWD

Typical reverse recovered energy loss as a function of collector current

$$E_{rec} = f(I_C)$$



With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$

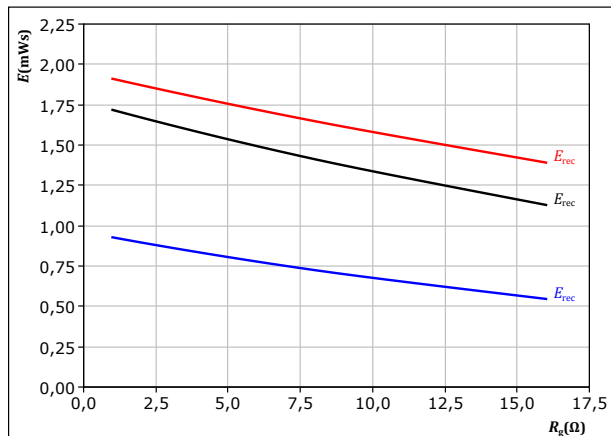
T_j : — 25 °C
— 125 °C
— 150 °C

figure 21.

FWD

Typical reverse recovered energy loss as a function of gate resistor

$$E_{rec} = f(R_g)$$



With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 100 \text{ A}$

T_j : — 25 °C
— 125 °C
— 150 °C



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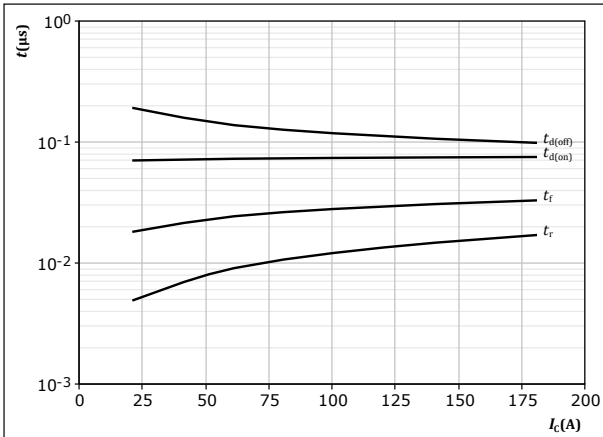
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datasheet

Buck Switching Characteristics

figure 22.

IGBT

Typical switching times as a function of collector current
 $t = f(I_c)$



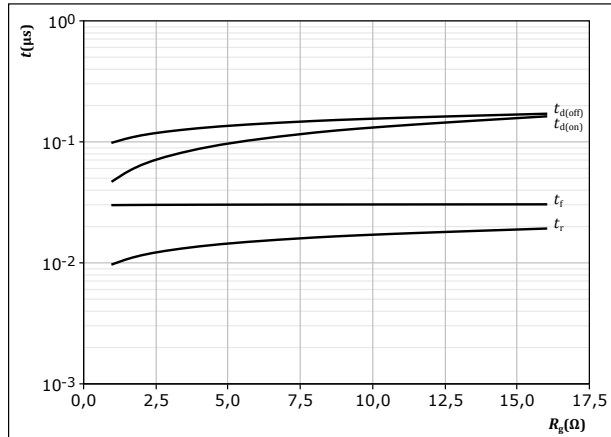
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω

figure 23.

IGBT

Typical switching times as a function of gate resistor
 $t = f(R_g)$



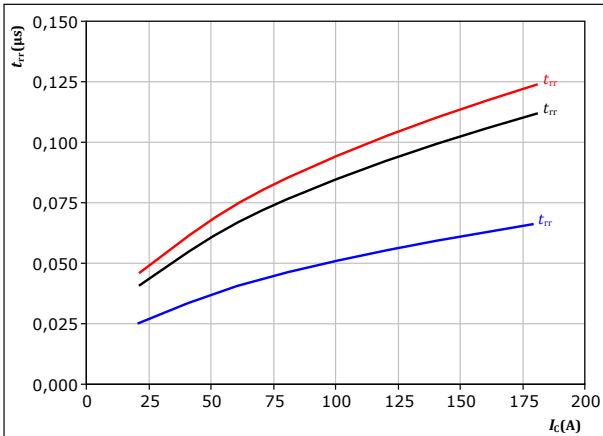
With an inductive load at

$T_j = 150$ °C
 $V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 100$ A

figure 24.

FWD

Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_c)$



With an inductive load at

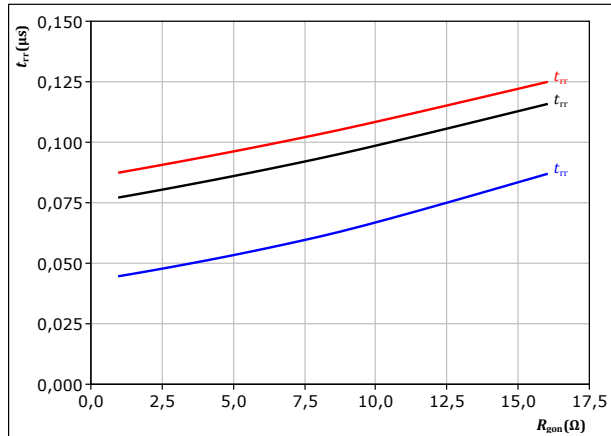
$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j : 25 °C
125 °C
150 °C

figure 25.

FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 100$ A

T_j : 25 °C
125 °C
150 °C



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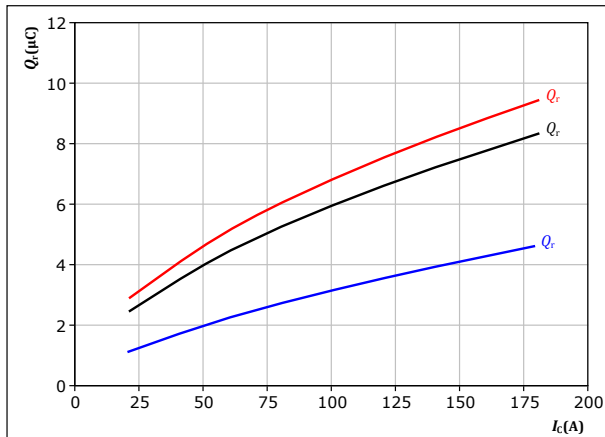
Buck Switching Characteristics

figure 26.

FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

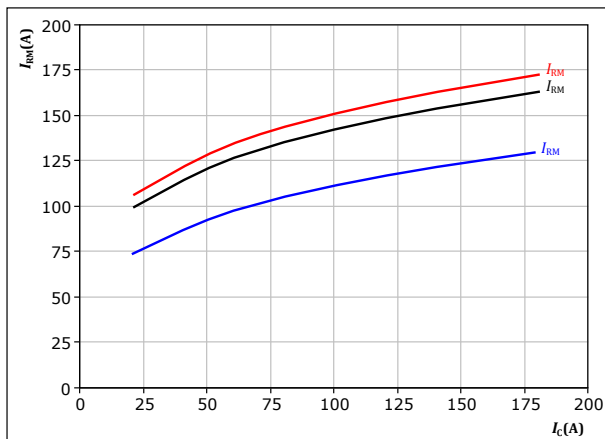
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 28.

FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

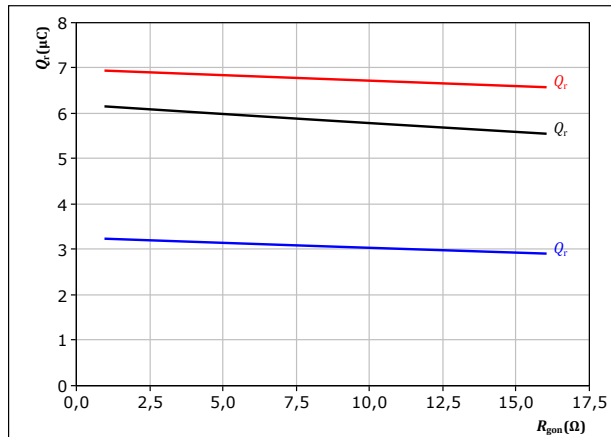
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 27.

FWD

Typical recovered charge as a function of turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 100$ A

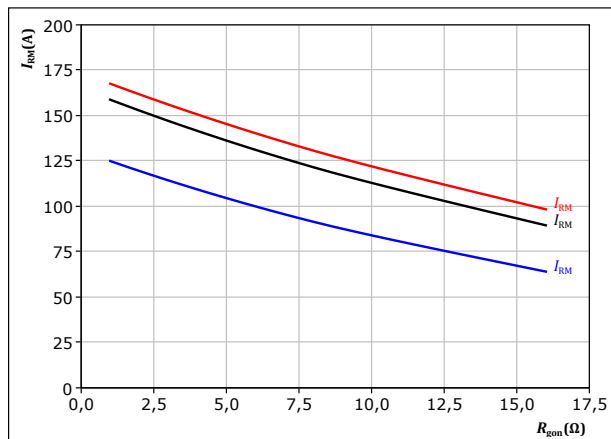
T_j :
— 25 °C
— 125 °C
— 150 °C

figure 29.

FWD

Typical peak reverse recovery current as a function of turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 100$ A

T_j :
— 25 °C
— 125 °C
— 150 °C



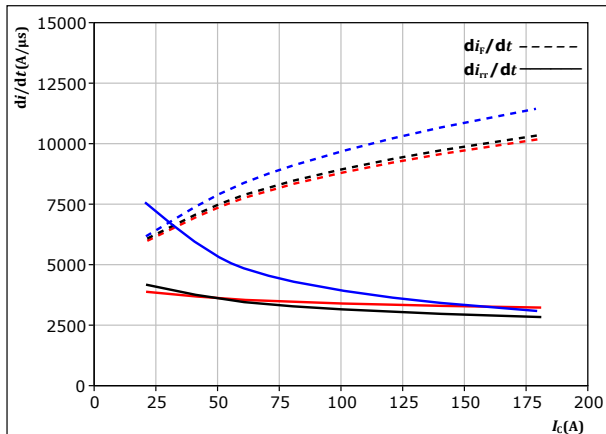
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datasheet

Buck Switching Characteristics

figure 30. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$



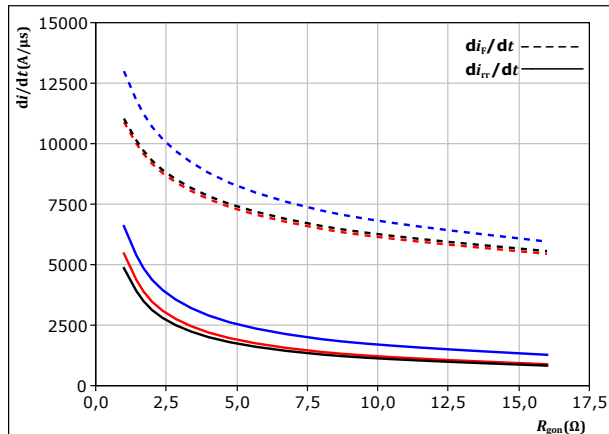
With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$

$T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 31. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



With an inductive load at

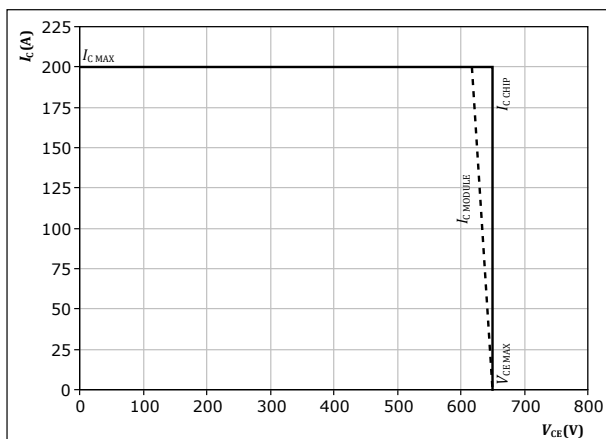
$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 100 \text{ A}$

$T_j:$ — 25 °C
— 125 °C
— 150 °C

figure 32. IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 150 \text{ } ^\circ\text{C}$
 $R_{gon} = 4 \text{ } \Omega$
 $R_{goff} = 4 \text{ } \Omega$



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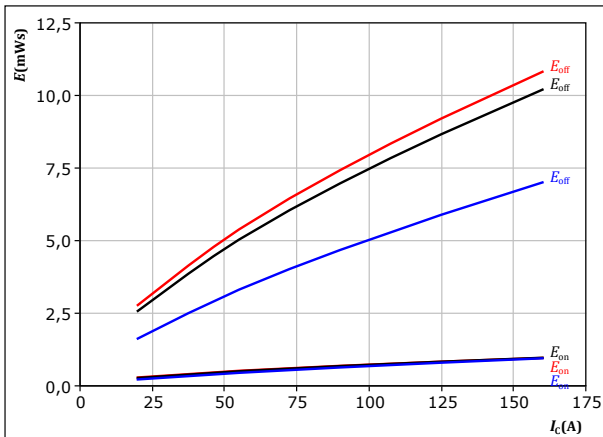
Boost Switching Characteristics

figure 33.

IGBT

Typical switching energy losses as a function of collector current

$$E = f(I_C)$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω

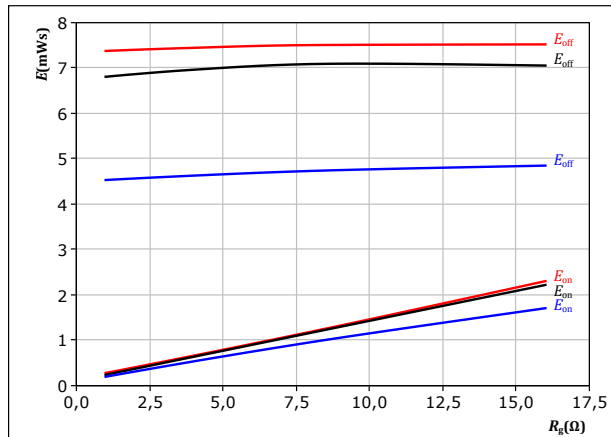
T_j : 25 °C
125 °C
150 °C

figure 34.

IGBT

Typical switching energy losses as a function of gate resistor

$$E = f(R_g)$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_C = 90$ A

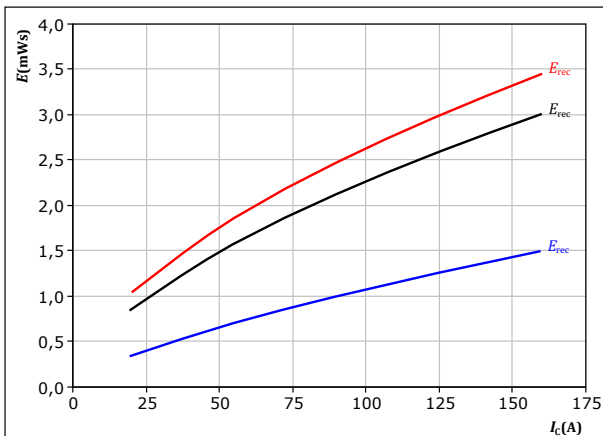
T_j : 25 °C
125 °C
150 °C

figure 35.

FWD

Typical reverse recovered energy loss as a function of collector current

$$E_{rec} = f(I_C)$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

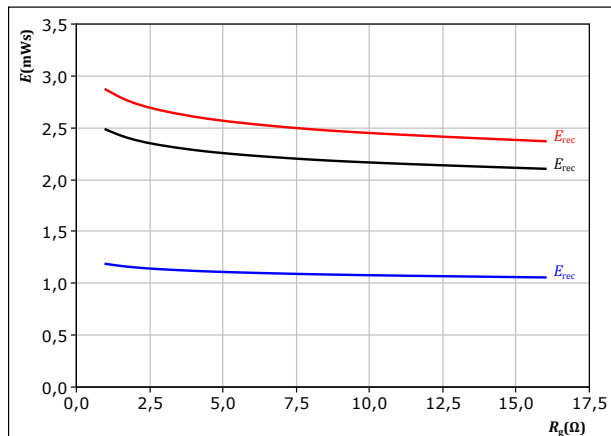
T_j : 25 °C
125 °C
150 °C

figure 36.

FWD

Typical reverse recovered energy loss as a function of gate resistor

$$E_{rec} = f(R_g)$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_C = 90$ A

T_j : 25 °C
125 °C
150 °C



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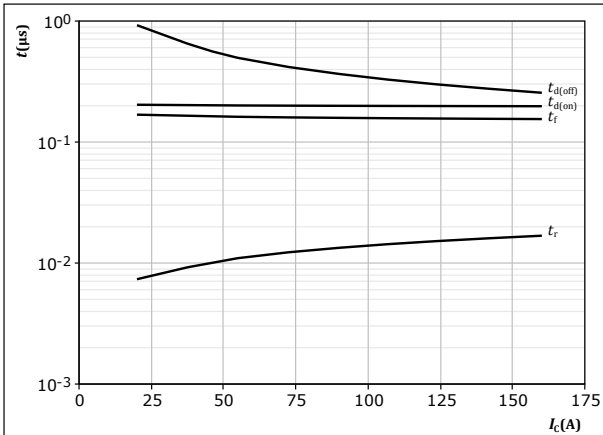
Boost Switching Characteristics

figure 37.

IGBT

Typical switching times as a function of collector current

$$t = f(I_c)$$



With an inductive load at

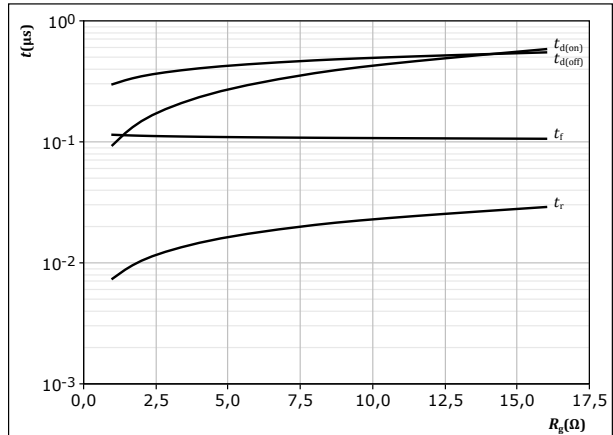
$T_j = 150 \text{ } ^\circ\text{C}$
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$
 $R_{goff} = 4 \text{ } \Omega$

figure 38.

IGBT

Typical switching times as a function of gate resistor

$$t = f(R_g)$$



With an inductive load at

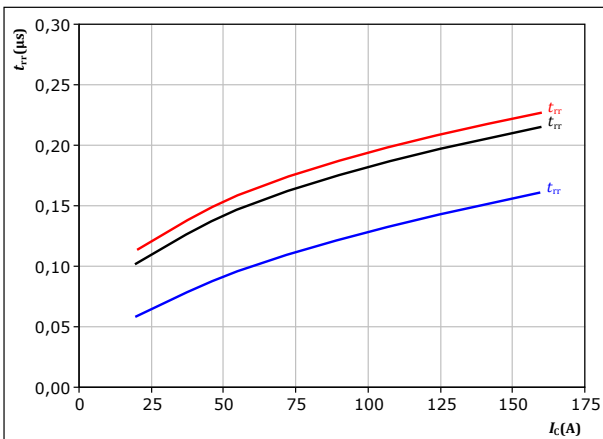
$T_j = 150 \text{ } ^\circ\text{C}$
 $V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 90 \text{ A}$

figure 39.

FWD

Typical reverse recovery time as a function of collector current

$$t_{rr} = f(I_c)$$



With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 4 \text{ } \Omega$

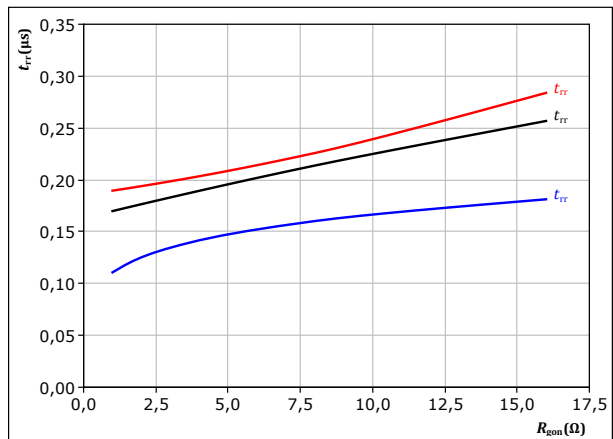
T_j :
 — 25 °C
 — 125 °C
 — 150 °C

figure 40.

FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$$t_{rr} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 350 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 90 \text{ A}$

T_j :
 — 25 °C
 — 125 °C
 — 150 °C



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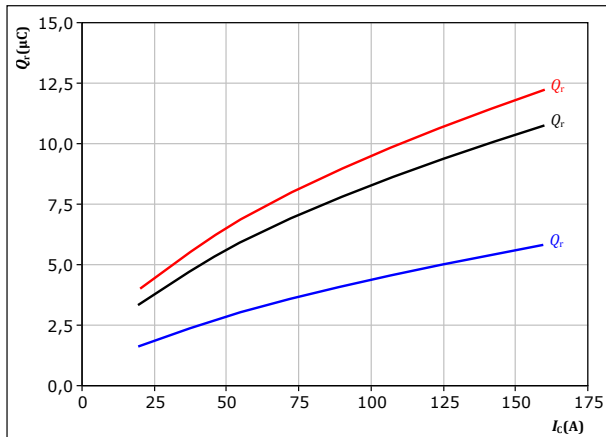
Boost Switching Characteristics

figure 41.

FWD

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



With an inductive load at

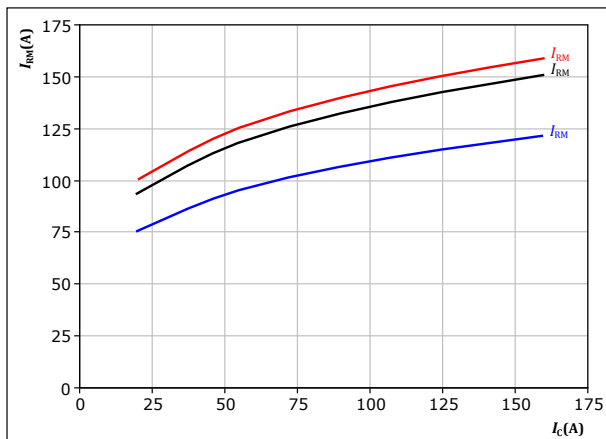
$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 43.

FWD

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$



With an inductive load at

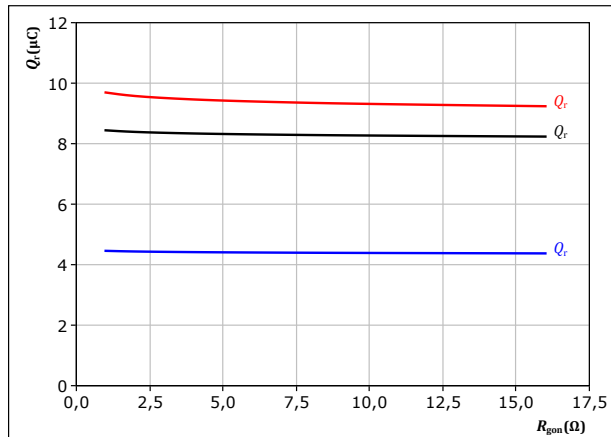
$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 42.

FWD

Typical recovered charge as a function of turn on gate resistor

$$Q_r = f(R_{gon})$$



With an inductive load at

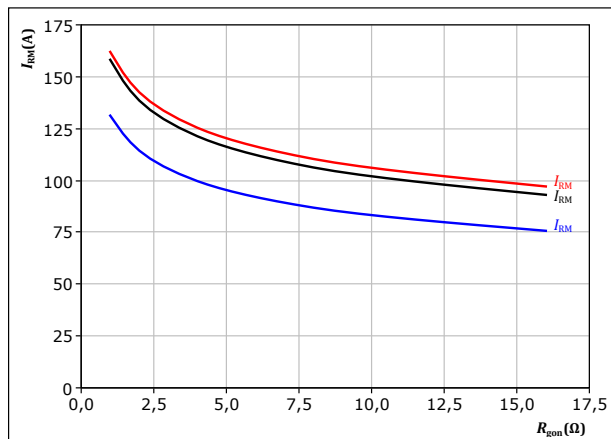
$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 90$ A
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)

figure 44.

FWD

Typical peak reverse recovery current as a function of turn on gate resistor

$$I_{RM} = f(R_{gon})$$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_c = 90$ A
 T_j : 25 °C (blue), 125 °C (black), 150 °C (red)



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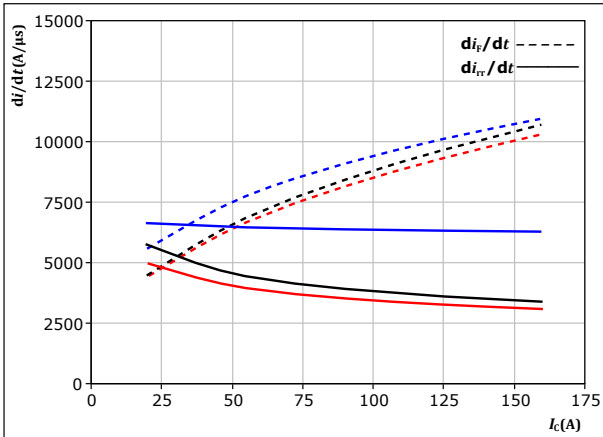
10-FY07NIA100S503-M515F58
datasheet

Boost Switching Characteristics

figure 45.

FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current
 $di_f/dt, di_r/dt = f(I_C)$



With an inductive load at

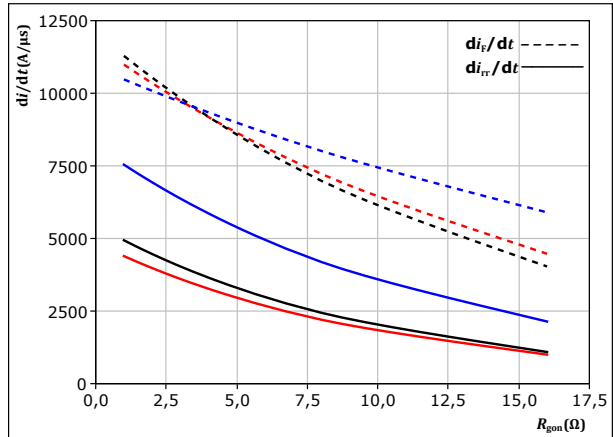
$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $R_{gon} = 4$ Ω

T_j : 25 °C
125 °C
150 °C

figure 46.

FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor
 $di_f/dt, di_r/dt = f(R_{gon})$



With an inductive load at

$V_{CE} = 350$ V
 $V_{GE} = \pm 15$ V
 $I_C = 90$ A

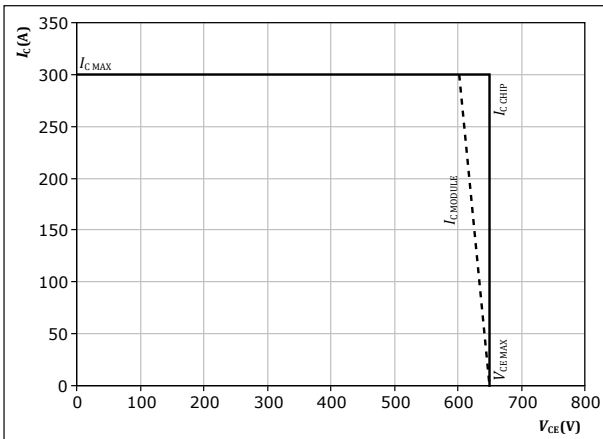
T_j : 25 °C
125 °C
150 °C

figure 47.

IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At $T_j = 150$ °C
 $R_{gon} = 4$ Ω
 $R_{goff} = 4$ Ω



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Switching Definitions

figure 48. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

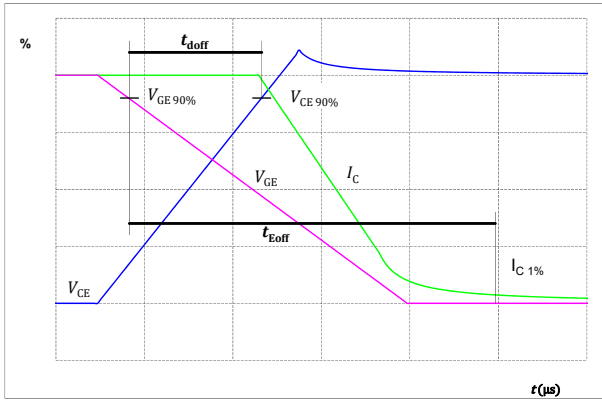


figure 49. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})



figure 50. IGBT

Turn-off Switching Waveforms & definition of t_f

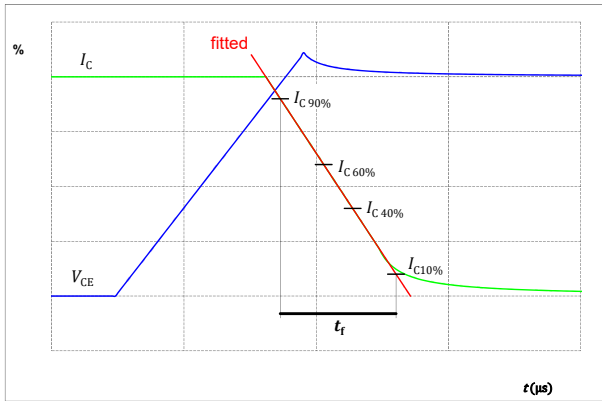
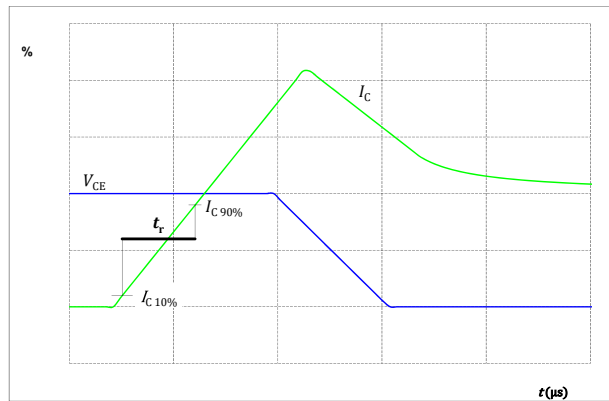


figure 51. IGBT

Turn-on Switching Waveforms & definition of t_r





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Switching Definitions

figure 52.

FWD

Turn-off Switching Waveforms & definition of t_{rr}

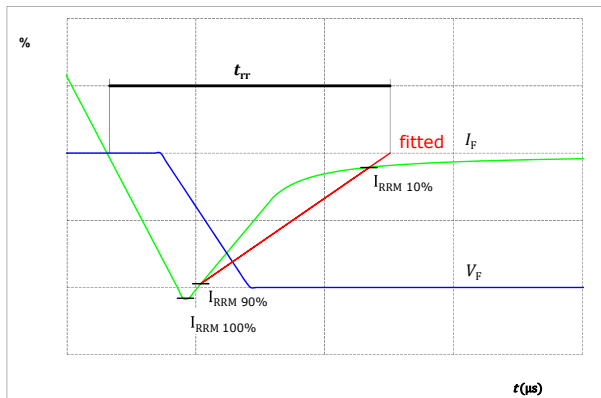
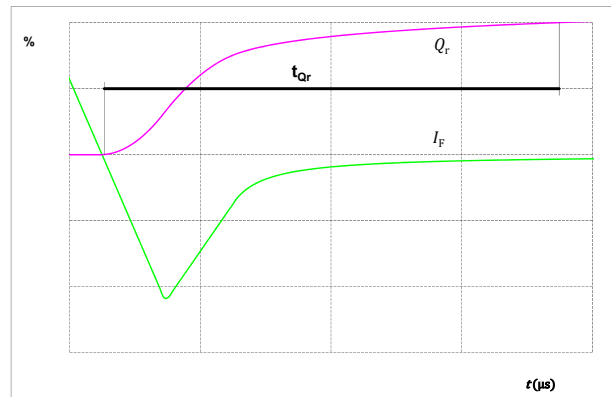


figure 53.

FWD



Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)





datasheet

Ordering Code	
Version	Ordering Code
Without thermal paste	10-FY07NIA100S503-M515F58
With thermal paste	10-FY07NIA100S503-M515F58-/3/

Marking							
<div><div>NN-NNNNNNNNNNNNNN TTTTTV WWYV UL VIN LLLL SSSS</div><div></div><div></div><div><div>VIN</div><div>Code</div><div>Brand</div><div>Model</div><div>Color</div><div>Date</div></div></div>	Text	Name		Date code	UL & VIN	Lot	Serial
		NN-NNNNNNNNNNNNNN- TTTTTV		WWYV	UL VIN	LLLLL	SSSS
	Datamatrix	Type&Ver	Lot number	Serial	Date code		
		TTTTTTVV	LLLLL	SSSS	WWYV		

Outline

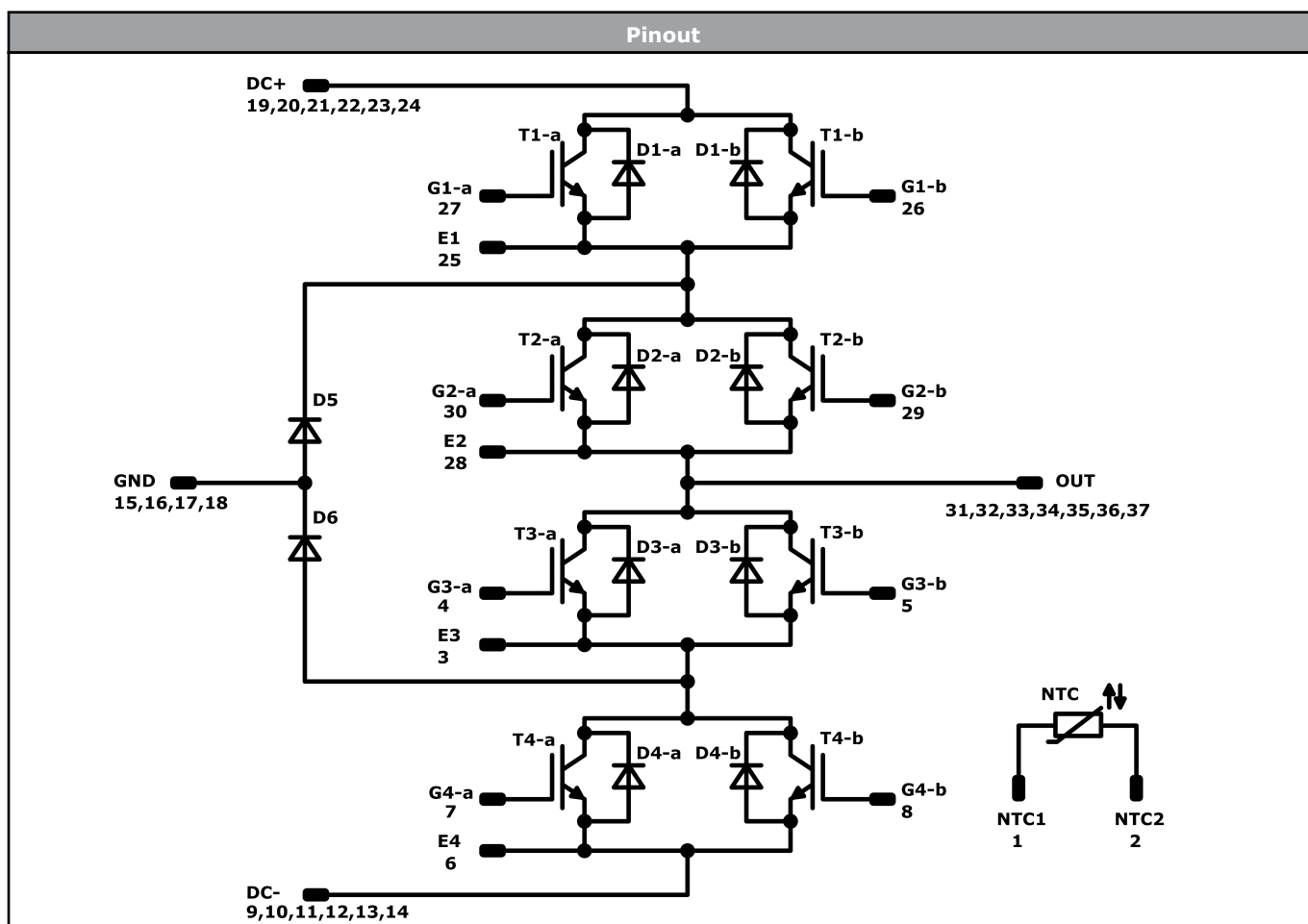
Pin table [mm]			
Pin	X	Y	Function
1	52,2	6,9	NTC1
2	52,2	0	NTC2
3	36,2	6,75	E3
4	33,2	7,9	G3-a
5	33,2	4,9	G3-b
6	9,2	5,75	E4
7	6,2	6,9	G4-a
8	6,2	3,9	G4-b
9	2,7	0	DC-
10	0	0	DC-
11	2,7	2,7	DC-
12	0	2,7	DC-
13	2,7	5,4	DC-
14	0	5,4	DC-
15	2,7	12,75	GND
16	0	12,75	GND
17	2,7	15,45	GND
18	0	15,45	GND
19	2,7	22,8	DC+
20	0	22,8	DC+
21	2,7	25,5	DC+
22	0	25,5	DC+
23	2,7	28,2	DC+
24	0	28,2	DC+
25	18,3	22,45	E1
26	21,3	21,3	G1-b
27	21,3	24,3	G1-a
28	43	22,15	E2
29	46	21	G2-b
30	46	24	G2-a
31	52,2	20,1	OUT
32	49,5	22,8	OUT
33	52,2	22,8	OUT
34	49,5	25,5	OUT
35	52,2	25,5	OUT
36	49,5	28,2	OUT
37	52,2	28,2	OUT

The technical drawing illustrates the physical dimensions and pin configuration of the sensor module. The top view shows a rectangular component with a central circular feature and four mounting holes at the corners. Pin locations are numbered 1 through 37, corresponding to the pin table. Key dimensions include a width of 26.1 mm and a height of 14.1 mm. The side view shows the module's profile with a height of 16.2 ±0.5 mm and a pin diameter of Φ 1 ±0.05 mm. A coordinate system (X, Y) is defined at the bottom left corner of the module.

Tolerance of pinpositions: ±0.5mm at the end of pins
 Dimension of coordinate axis is only offset without tolerance



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Identification					
ID	Component	Voltage	Current	Function	Comment
T1, T4	IGBT	650 V	100 A	Buck Switch	
D5, D6	FWD	650 V	100 A	Buck Diode	
T2, T3	IGBT	650 V	150 A	Boost Switch	
D4, D1	FWD	650 V	100 A	Boost Diode	
D3, D2	FWD	650 V	100 A	Boost Sw. Inv. Diode	
NTC	Thermistor			Thermistor	



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datasheet

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample
Handling instruction				
Handling instructions for <i>flow</i> 1 packages see vincotech.com website.				
Package data				
Package data for <i>flow</i> 1 packages see vincotech.com website.				
Vincotech thermistor reference				
See Vincotech thermistor reference table at vincotech.com website.				
UL recognition and file number				
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.				

Document No.:	Date:	Modification:	Pages
10-FY07NIA100S503-M515F58-D2-14	1 Apr. 2020	Update Boost Switch Rth	
10-FY07NIA100S503-M515F58-D3-14	14 Oct. 2020	Correction of function names in Pin table Change of voltage from 1200V to 650V on header	

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.